



(2.54 mm) .100"

HLE SERIES

COST-EFFECTIVE RELIABLE SOCKET

Mates With:
TSW, MTSW, DW,
EW, ZW, TLW, TSM,
MTLW, HW

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?HLE

Insulator Material:
Black Liquid Crystal Polymer
Contact Material:
BeCu
Plating:
Au or Sn over
50 μ" (1.27 μm) Ni
Current Rating (HLE/TSM):
4.1 A per pin
(1 pin powered per row)
Voltage Rating:
400 VAC
Operating Temp Range:
-55 °C to +125 °C
Insertion Depth:
(1.78 mm) .070" to
(3.43 mm) .135", pass-through,
or (2.59 mm) .102" min
plus board thickness for
bottom entry
RoHS Compliant:
Yes

PROCESSING

Lead-Free Solderable:
Yes
SMT Lead Coplanarity:
(0.10 mm) .004" max (02-20)
(0.15 mm) .006" max (21-50)

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



ALSO AVAILABLE
(MOQ Required)

- Other platings
- Contact Samtec.

Note: Some lengths, styles and options are non-standard, non-returnable.

HLE	1	NO. PINS PER ROW	02	PLATING OPTION	DV	TAIL OPTION	OTHER OPTION	
02 thru 50				-F = Gold flash on contact, Matte Tin on tail	Leave blank for Surface Mount			-BE = Bottom Entry (N/A with -TE)
				-L = 10 μ" (0.25 μm) Gold on contact, Matte Tin on tail				-A = Alignment Pin (4 positions min.) Metal or plastic at Samtec discretion (N/A with -TE, -PE & -LC)
				 (Requires -BE for Bottom Entry)			-LC = Locking Clip (2 positions min.) (N/A with -A) (Manual placement required)	
							-TE = Through-hole Top Entry	-K = (6.50 mm) .256" DIA Polyimide Film Pick & Place Pad (3 positions min.) Not available with -TE or -PE tail option
							-PE = Through-hole Pass-through Entry	
							-P = Metal Pick & Place Pad (3 positions min.)	
				 (Requires -BE for Bottom Entry)			-TR = Tape & Reel Packaging (29 positions max.)	